# INTEGRATED CIRCUITS

# DATA SHEET

# TDF5242T Brushless DC motor drive circuit

Preliminary specification Supersedes data of 1997 Apr 23 File under Integrated Circuits, IC11





#### **TDF5242T**

#### **FEATURES**

- Full-wave commutation without position sensors
- · Built-in start-up circuitry
- Six outputs that can drive three external transistor pairs:
  - output current 0.2 A (typ.)
  - low saturation voltage
  - built-in current limiter
- · Thermal protection
- · Tacho output without extra sensor
- Transconductance amplifier for an external control transistor
- · Brake control input
- · Direction control input.

#### **APPLICATIONS**

- High-power applications, for instance:
  - high-end hard disk drives
  - automotive applications.

#### **GENERAL DESCRIPTION**

The TDF5242T is a bipolar integrated circuit for driving 3-phase brushless DC motors in full-wave mode. The device functions sensorless, thus saving 3 hall-effect sensors, using the back-EMF (Electro Motive Force) sensing technique to sense the rotor position. It includes 6 pre-drivers able to control external FETs (Field Effect Transistors) or bipolar transistors. It offers brake and direction control. It is ideally suited for high-power applications such as high-end hard disk drives and automotive applications.

#### QUICK REFERENCE DATA

Measured over full voltage and temperature range.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>P</sub>	supply voltage	note 1	4	_	18	٧
V <sub>VMOT</sub>	input voltage to the output driver stages		3	_	18	V
Vo	driver output voltage	I <sub>O</sub> = 100 mA; lower transistor	_	_	0.35	V
		I <sub>O</sub> = 100 mA; upper transistor	1.05	_	_	٧
I <sub>LIM</sub>	current limiting	$V_{VMOT} = 14.5 \text{ V}; R_O = 47 \Omega$	150	200	250	mA

#### Note

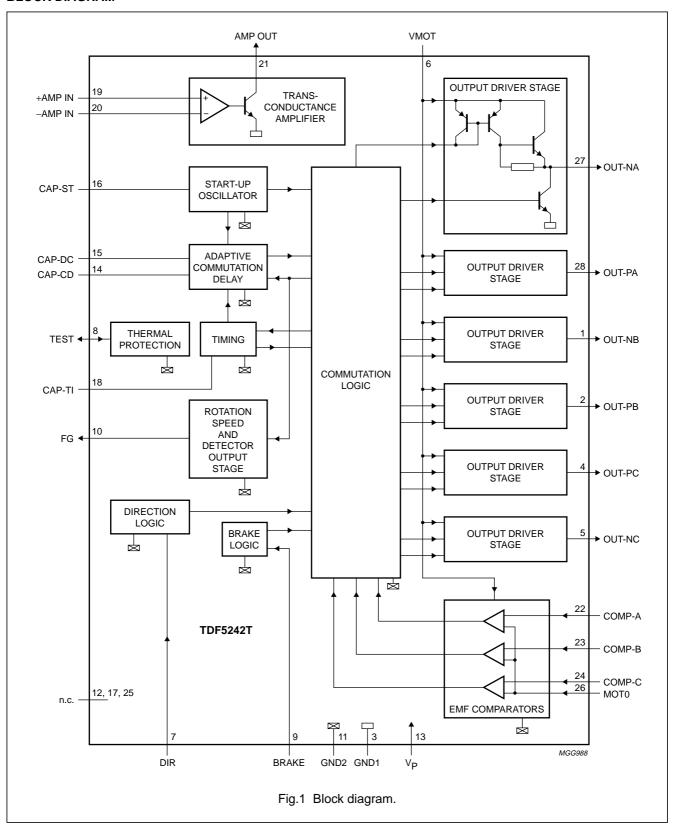
1. An unstabilized supply can be used.

#### **ORDERING INFORMATION**

TYPE		PACKAGE							
NUMBER	NUMBER DESCRIPTION VERSI								
TDF5242T	SO28	plastic small outline package; 28 leads; body width 7.5 mm	SOT136-1						

# **TDF5242T**

#### **BLOCK DIAGRAM**



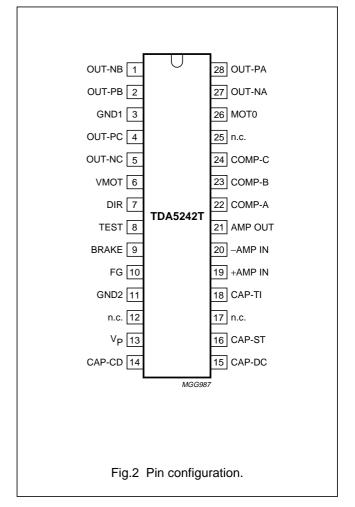
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**TDF5242T** 

#### **PINNING**

SYMBOL	PIN	DESCRIPTION		
OUT-NB	1	driver output B for driving the n-channel power FET or power NPN		
OUT DD	-	·		
OUT-PB	2	driver output B for driving the p-channel power FET or power PNP		
GND1	3	ground (0 V) motor supply return for output stages		
OUT-PC	4	driver output C for driving the p-channel power FET or power PNP		
OUT-NC	5	driver output C for driving the n-channel power FET or power NPN		
VMOT	6	input voltage for the output driver stages		
DIR	7	direction input command		
TEST	8	test input/output		
BRAKE	9	brake input		
FG	10	frequency generator: output of the rotation speed detector stage		
GND2	11	ground supply return for control circuits		
n.c.	12	not connected		
V <sub>P</sub>	13	supply voltage		
CAP-CD	14	external capacitor connection for adaptive communication delay timing		
CAP-DC	15	external capacitor connection for adaptive communication delay timing copy		
CAP-ST	16	external capacitor connection for start-up oscillator		
n.c.	17	not connected		
CAP-TI	18	external capacitor connection for timing		
+AMP IN	19	non-inverting input of the transconductance amplifier		
-AMP IN	20	inverting input of the transconductance amplifier		
AMP OUT	21	transconductance amplifier output (open collector)		
COMP-A	22	comparator input corresponding to output A		

SYMBOL	PIN	DESCRIPTION
COMP-B	23	comparator input corresponding to output B
COMP-C	24	comparator input corresponding to output C
n.c.	25	not connected
МОТ0	26	input from the star point of the motor coils
OUT-NA	27	driver output A for driving the n-channel power FET or power NPN
OUT-PA	28	driver output A for driving the p-channel power FET or power PNP



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#### **FUNCTIONAL DESCRIPTION**

#### Introduction

Full-wave driving of a three phase motor requires three push-pull output stages. In each of the six possible states two outputs are active, one sourcing (H) and one sinking (L). The third output presents a high impedance (Z) to the motor, which enables measurement of the motor back-EMF (Electro Motive Force) in the corresponding motor coil by the EMF comparator at each output. The commutation logic is responsible for control of the output transistors and selection of the correct EMF comparator. In Table 1, the six possible states of the externally connected output transistors have been depicted and the corresponding output levels on the NA, PA, NB, PB, NC and PC outputs of the TDF5242T.

The zero-crossing in the motor EMF (detected by the comparator selected by the commutation logic) is used to calculate the correct moment for the next commutation, that is, the change to the next output state. The delay is calculated (depending on the motor loading) by the adaptive commutation delay block.

The output stages are protected by a current limiting circuit and by thermal protection.

The detected zero-crossings are used to provide speed information. The information has been made available on the FG output pin. This output provides an output signal with a frequency equal to the commutation frequency.

The system will only function when the EMF voltage from the motor is present. Therefore, a start oscillator is provided that will generate commutation pulses when no zero-crossings in the motor voltage are available.

A timing function is incorporated into the device for internal timing and for timing of the reverse rotation detection.

The TDF5242T also contains an uncommitted transconductance amplifier (OTA) that can be used as a control amplifier. The output is capable of directly driving an external power transistor.

The TDF5242T is designed for systems with low current consumption. It uses I<sup>2</sup>L logic and adaptive base drive for the output transistors (patented).

#### Start-up and commutation control

The system has been designed in such a way that the tolerances of the application components are not critical. However, the approximate values of the following components must still be determined:

- The start capacitor; this determines the frequency of the start oscillator
- The two capacitors in the adaptive commutation delay circuit; these are important in determining the optimum moment for commutation, depending on the type and loading of the motor
- The timing capacitor; this provides the system with its timing signals.

Table 1 Output states (note 1)

DIR	STATE	MOT1	OUT-NA	OUT-PA	MOT2	OUT-NB	оит-рв	МОТ3	OUT-NC	OUT-PC
Н	1	Z	L	Н	L	Н	Н	Н	L	L
Н	2	Н	L	L	L	Н	Н	Z	L	Н
Н	3	Н	L	L	Z	L	Н	L	Н	Н
Н	4	Z	L	Н	Н	L	L	L	Н	Н
Н	5	L	Н	Н	Н	L	L	Z	L	Н
Н	6	L	Н	Н	Z	L	Н	Н	L	L
L	1	Z	L	Н	L	Н	Н	Н	L	L
L	2	L	Н	Н	Z	L	Н	Н	L	L
L	3	L	Н	Н	Н	L	L	Z	L	Н
L	4	Z	L	Н	Н	L	L	L	Н	Н
L	5	Н	Ĺ	L	Z	Ĺ	Н	Ĺ	Н	Н
L	6	Н	L	L	L	Н	Н	Z	L	Н

#### Note

1. H = HIGH state; L = LOW state; Z = high-impedance OFF-state.

**TDF5242T** 

START CAPACITOR (CAP-ST)

This capacitor determines the frequency of the start oscillator. It is charged and discharged, with a current of 2  $\mu$ A, from 0.05 to 2.2 V and back to 0.05 V. The time to complete one cycle is:

$$t_{start} = (2.15 \times C) \text{ s (with C in } \mu\text{F )}$$
 (1)

The start oscillator is reset by a commutation pulse and is only active when the system is in the start-up mode. A pulse from the start oscillator will cause the outputs to change to the next state. If the movement of the motor generates enough EMF, the TDF5242T will run the motor. If the amount of EMF generated is insufficient, then the motor will move one step only and will oscillate in its new position. The amplitude of the oscillation must decrease sufficiently before the arrival of the next start pulse, to prevent the pulse arriving during the wrong phase of the oscillation. The start capacitor should be chosen to meet this requirement.

The oscillation frequency of the motor is given by:

$$f_{osc} = \frac{1}{2\pi \sqrt{\frac{K_t \times I \times p}{J}}}$$

where

K<sub>t</sub> = torque constant (Nm/A)

I = current (A)

p = number of magnetic pole-pairs

J = inertia J (kg.m<sup>2</sup>).

Example:  $J = 72 \times 10^{-6} \text{ kg.m}^2$ ,  $K = 25 \times 10^{-3} \text{ Nm/A}$ , p = 6 and I = 0.5 A; this gives  $f_{osc} = 5 \text{ Hz}$ . If the damping is high, a start frequency of 2 Hz can be chosen or t = 500 ms, thus, according to equation (1):  $C = 0.5/2.15 = 0.23 \mu\text{F}$  (choose 220 nF).

ADAPTIVE COMMUTATION DELAY (CAP-CD AND CAP-DC)

In this circuit the capacitor CAP-CD is charged during one commutation period, with an interruption of the charging current during the diode pulse. During the next commutation period the capacitor is discharged at twice the charging current. The charging current is 8.1  $\mu A$  and the discharging current 16.2  $\mu A$ ; the voltage range is from 0.9 to 2.2 V. The voltage must stay within this range at the lowest commutation frequency of interest,  $f_{C1}$ :

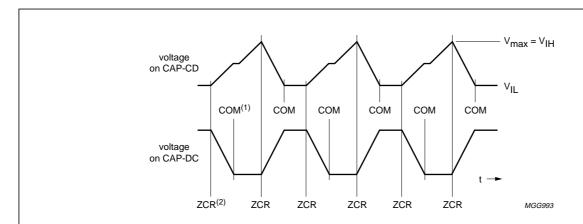
$$C = \frac{8.1 \times 10^{-6}}{f \times 1.3} = \frac{6231}{f_{C1}} (C \text{ in nF})$$

If the commutation frequency is lower, a constant commutation delay after the zero-crossing is generated by the discharge from 2.2 down to 0.9 V at 16.2  $\mu$ A; maximum delay = (0.076 × C) ms (with C in nF)

Example: nominal commutation frequency = 900 Hz and the lowest usable frequency = 400 Hz; so:

CAP-CD = 
$$\frac{6231}{400}$$
 = 15.6 (choose 18 nF)

The other capacitor, CAP-DC, is used to repeat the same delay by charging and discharging with 15.5  $\mu$ A. The same value can be chosen as for CAP-CD. Figure 3 illustrates typical voltage waveforms.



- (1) COM = commutation.
- (2) ZCR = zero-crossing.

Fig.3 CAP-CD and CAP-DC typical voltage waveforms in normal running mode.

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THE TIMING CAPACITOR (CAP-TI)

Capacitor CAP-TI is used for timing the successive steps within one commutation period; these steps include some internal delays.

The most important function is the watchdog time in which the motor EMF has to recover from a negative diode-pulse back to a positive EMF voltage (or vice versa). A watchdog timer is a guarding function that only becomes active when the expected event does not occur within a predetermined time

The EMF usually recovers within a short time if the motor is running normally (<<1 ms). However, if the motor is motionless or rotating in the reverse direction, the time can be longer (>>1 ms).

A watchdog time must be chosen such that it is long enough for a motor without detectable EMF, however, it must be short enough to detect reverse rotation. If the watchdog time is made too long, then the motor may run in the wrong direction (with little torque).

The capacitor is charged with a current of 57  $\mu$ A from 0.2 to 0.3 V. Above this level, it is charged with a current of 5  $\mu$ A up to 2.2 V only if the selected motor EMF remains in the wrong polarity (watchdog function). At the end, or, if the motor voltage becomes positive, the capacitor is discharged with a current of 28  $\mu$ A. The watchdog time is the time taken to charge the capacitor, with a current of 5  $\mu$ A, from 0.3 to 2.2 V.

To ensure that the internal delays are covered CAP-TI must have a minimum value of 2 nF. For the watchdog function a value for CAP-TI of 10 nF is recommended.

To ensure a good start-up and commutation, care must be taken that no oscillations occur at the trailing edge of the flyback pulse. Snubber networks at the outputs should be critically damped.

Typical voltage waveforms are illustrated by Fig.4.

#### Miscellaneous functions

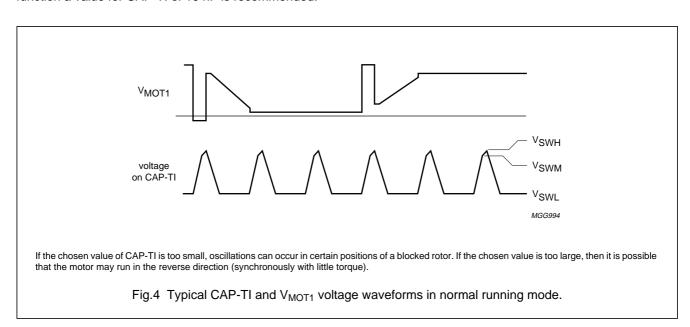
In addition to start-up and commutation control, the TDF5242T provides the following functions:

- · Generation of the tacho signal FG
- General purpose Operational Transconductance Amplifier (OTA)
- · Possibilities of motor control
- Direction function and brake function
- · High current and temperature protection.

THE OPERATIONAL TRANSCONDUCTANCE AMPLIFIER (OTA)

The OTA is an uncommitted amplifier with a high output current (40 mA) that can be used as a control amplifier or as a level converter in a Switched Mode Power Supply (SMPS). The common mode input range includes ground (GND) and rises to  $V_P-1.7$  V. The high sink current enables the OTA to drive a power transistor directly in an analog control amplifier or in a SMPS driver.

Although the gain is not extremely high (0.3 S), care must be taken with the stability of the circuit if the OTA is used as a linear amplifier as no frequency compensation is provided.



**TDF5242T** 

The convention for the inputs (inverting or not) is the same as for a normal operational amplifier: with a resistor (as a load) connected from the output (AMP OUT) to the positive supply, a positive-going voltage is found when the non-inverting input (+AMP IN) is positive with respect to the inverting input (-AMP IN). Note that a 'plus' input causes less current, and consequently a positive voltage.

#### MOTOR CONTROL

DC motors can also be operated with analog control using the OTA.

For the analog control an external transistor is required. The OTA can supply the base current for this transistor and act as a control amplifier (see Fig.8).

#### FG SIGNAL

The FG (Frequency Generator) signal is generated in the TDF5242T by using the zero-crossing of the motor EMF from the three motor windings and the commutation signal.

Output FG switches from HIGH-to-LOW on all zero crossings and from LOW-to-HIGH on all commutations. Output FG can source typically 75  $\mu$ A and sink more than 3 mA.

Example: a 3-phase motor with 6 magnetic pole-pairs at 1500 rpm and with a full-wave drive has a commutation frequency of  $25 \times 6 \times 6 = 900$  Hz, and generates a tacho signal of 900 Hz.

#### **DIRECTION FUNCTION**

- If the voltage on pin 7 is <2.3 V the motor is running in one direction (depending on the motor connections)
- If pin 7 is floating or the voltage is >2.7 V the motor is running in the other direction.

#### **BRAKE FUNCTION**

- If the voltage on pin 9 (pin BRAKE) is <2.3 V the motor brakes; in this condition the external outputs are driven to a HIGH voltage level
- If pin 9 is floating or the voltage is >2.7 V the motor runs normally.

#### RELIABILITY

The output stages are protected in two ways:

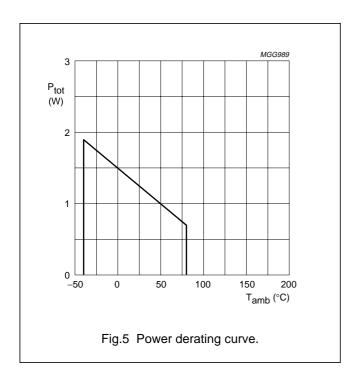
- Current limiting of the 'lower' output transistors.
   The 'upper' output transistors use the same base current as the conducting 'lower' transistor (+15%).
   This means that the current to and from the output stages is limited.
- Thermal protection of the six output transistors is achieved in such a way that the transistors are switched off when the junction temperature becomes too high.

**TDF5242T** 

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>P</sub>	supply voltage		4	18	V
Vı	input voltage; all pins except VMOT, CAP-ST, CAP-TI, CAP-CD and CAP-DC	V <sub>I</sub> < 18 V	-0.3	V <sub>P</sub> + 0.5	V
V <sub>VMOT</sub>	VMOT input voltage		3	18	V
Vo	output voltage				
	FG		GND	V <sub>P</sub>	V
	AMP OUT		_	18	V
	OUT-NA, OUT-NB and OUT-NC		_	V <sub>VMOT</sub> – 0.9	V
	OUT-PA, OUT-PB and OUT-PC		0.2	_	V
VI	input voltage CAP-ST, CAP-TI, CAP-CD and CAP-DC		_	2.5	V
T <sub>stg</sub>	storage temperature		-55	+150	°C
T <sub>amb</sub>	operating ambient temperature		-40	+85	°C
P <sub>tot</sub>	total power dissipation	see Fig.5	_	_	
V <sub>es</sub>	electrostatic handling	see Chapter "Handling"	_	500	V



#### **HANDLING**

Every pin withstands the ESD test according to "MIL-STD-883C class 2". Method 3015 (HBM 1500  $\Omega$ , 100 pF) 3 pulses + and 3 pulses – on each pin referenced to ground.

#### **QUALITY SPECIFICATION**

In accordance with "SNW-FQ-611-E". The number of the quality specification can be found in the "Quality Reference Handbook". The handbook can be ordered using the code 9397 750 00192.

TDF5242T

#### **CHARACTERISTICS**

 $V_P$  = 14.5 V ±10%;  $T_{amb}$  = –40 to +85  $^{\circ}C$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply			!	'	'	•
V <sub>P</sub>	supply voltage	note 1	4	_	18	V
I <sub>P</sub>	supply current	note 2	_	5.2	6.25	mA
V <sub>VMOT</sub>	input voltage to the output driver stages	see Fig.1	3	_	18	V
Thermal pr	rotection					
T <sub>SD</sub>	temperature at temperature sensor causing shut-down		130	140	150	°C
ΔΤ	decrease in temperature before switch-on after shut-down		_	T <sub>SD</sub> – 30	_	К
COMP-A, C	COMP-B, COMP-C and MOT0					
VI	input voltage		-0.5	_	V <sub>VMOT</sub>	V
I <sub>I</sub>	input bias current	$0.5 \text{ V} < \text{V}_{\text{I}} < \text{V}_{\text{VMOT}} - 1.5 \text{ V}$	-10	_	0	μΑ
V <sub>CSW</sub>	comparator switching level	note 3	±20	±25	±30	mV
$\Delta V_{CSW}$	variation in comparator switching levels		-3	0	+3	mV
V <sub>hys</sub>	comparator input hysteresis	T <sub>amb</sub> = 25 °C	_	75	_	μV
OUT-NA, O	UT-NB, OUT-NC, OUT-PA, OUT-PB	and OUT-PC				
V <sub>O(n)</sub>	n-channel driver output voltage	upper transistor; I <sub>O</sub> = -100 mA; T <sub>amb</sub> = 25 °C	-1.05	_	_	V
		lower transistor; I <sub>O</sub> = 10 mA; T <sub>amb</sub> = 25 °C	_	-	0.35	V
V <sub>O(p)</sub>	p-channel driver output voltage	upper transistor; I <sub>O</sub> = -10 mA; T <sub>amb</sub> = 25 °C	-1.05	_	_	V
		lower transistor; I <sub>O</sub> = 100 mA; T <sub>amb</sub> = 25 °C	_	_	0.35	V
$\Delta V_{OL}$	variation in saturation voltage between lower transistors	I <sub>O</sub> = 100 mA; T <sub>amb</sub> = 25 °C	_	_	180	mV
$\Delta V_{OH}$	variation in saturation voltage between upper transistors	$I_O = -100 \text{ mA};$ $T_{amb} = 25 ^{\circ}\text{C}$	_	_	180	mV
I <sub>LIM</sub>	current limiting	lower transistor; $R_0 = 47 \Omega$	150	180	250	mA
+AMP IN a	nd -AMP IN					
VI	input voltage		-0.3	_	V <sub>P</sub> – 1.7	V
	differential mode voltage without 'latch-up'		_	_	±V <sub>P</sub>	V
I <sub>b</sub>	input bias current	T <sub>amb</sub> = 25 °C	_	_	650	nA
C <sub>I</sub>	input capacitance	T <sub>amb</sub> = 25 °C	_	4	-	pF
V <sub>offset</sub>	input offset voltage		_	_	10	mV

TDF5242T

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
AMP OUT	(open collector)			-	•	•
I <sub>sink</sub>	output sink current		40	_	_	mA
V <sub>sat</sub>	saturation voltage	I <sub>I</sub> = 40 mA	_	1.5	2.1	V
V <sub>O</sub>	output voltage		-0.5	-	+18	V
SR	slew rate	$R_L = 330 \Omega; C_L = 50 pF$	40	_	_	mA/μs
g <sub>m(tr)</sub>	transfer gain		0.3	_	_	S
DIR						
V <sub>IL</sub>	LOW level input voltage (reverse rotation)	reverse mode; 4 V < V <sub>P</sub> < 18 V	_	-	2.3	V
V <sub>IH</sub>	HIGH level input voltage (normal rotation)	normal mode; 4 V < V <sub>P</sub> < 18 V	2.7	-	_	V
I <sub>IL</sub>	LOW level input current (reverse rotation)	reverse mode; T <sub>amb</sub> = 25 °C	_	-20	_	μА
I <sub>IH</sub>	HIGH level input current (normal rotation)	normal mode; T <sub>amb</sub> = 25 °C	_	0	_	μА
BRAKE				•		•
$V_{BM}$	brake-mode voltage	enable brake mode; 4 V < V <sub>P</sub> < 18 V	_	-	2.3	V
		normal mode; 4 V < V <sub>P</sub> < 18 V	2.7	-	_	V
I	input current	brake mode; T <sub>amb</sub> = 25 °C	_	-20	-30	μΑ
		normal mode; T <sub>amb</sub> = 25 °C	_	0	20	μА
FG (push-	oull)					
V <sub>OL</sub>	LOW level output voltage	I <sub>O</sub> = 1.6 mA	_	_	0.4	V
V <sub>OH</sub>	HIGH level output voltage	$I_{O} = -60  \mu A$	_	V <sub>P</sub> - 0.3	-	V
t <sub>THL</sub>	HIGH-to-LOW transition time	$T_{amb} = 25 ^{\circ}\text{C};$ $C_L = 50  \text{pF};  R_L = 10  \text{k}\Omega$	_	0.5	_	μs
f <sub>FG</sub>	ratio of FG frequency and commutation frequency	T <sub>amb</sub> = 25 °C	_	1	_	
CAP-ST						
I <sub>sink</sub>	output sink current		1.5	2.0	2.5	μΑ
I <sub>source</sub>	output source current		-2.5	-2.0	-1.5	μΑ
V <sub>SWL</sub>	LOW level switching voltage	T <sub>amb</sub> = 25 °C	_	0.20	_	V
V <sub>SWH</sub>	HIGH level switching voltage	T <sub>amb</sub> = 25 °C	_	2.20	_	V

Philips Semiconductors Preliminary specification

# Brushless DC motor drive circuit

**TDF5242T** 

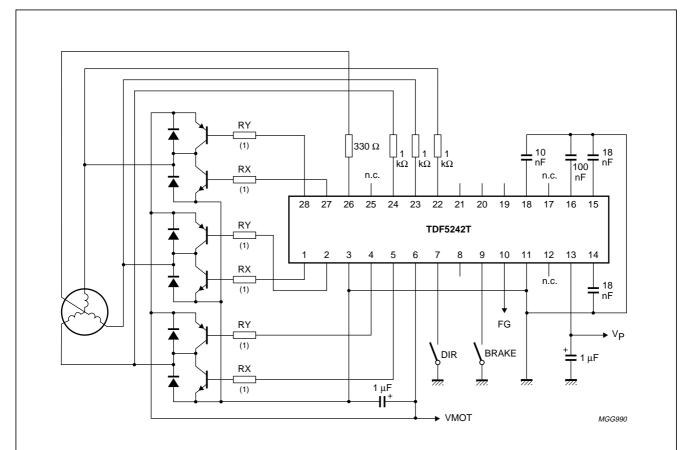
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
CAP-TI						•
I <sub>sink</sub>	output sink current		20	28	38	μΑ
I <sub>source</sub>	output source current	0.2 V < V <sub>CAP-TI</sub> < 0.3 V	-64	-57	-50	μΑ
		0.3 V < V <sub>CAP-TI</sub> < 2.2 V	-6.5	-5.5	-4.5	μΑ
V <sub>SWL</sub>	LOW level switching voltage	ning voltage T <sub>amb</sub> = 25 °C			_	mV
V <sub>SWM</sub>	MIDDLE level switching voltage	T <sub>amb</sub> = 25 °C	_	0.30	_	V
V <sub>SWH</sub>	HIGH level switching voltage	T <sub>amb</sub> = 25 °C	_	2.20	_	V
CAP-CD						•
I <sub>sink</sub>	output sink current		10.6	16.2	22	μΑ
I <sub>source</sub>	output source current		-5.3	-8.1	-11	μΑ
I <sub>sink</sub> /I <sub>source</sub>	ratio of sink to source current		1.85	2.05	2.25	
V <sub>IL</sub>	LOW level input voltage	T <sub>amb</sub> = 25 °C	825	850	875	mV
$\frac{\Delta V_{IL}}{\Delta T}$	temperature coefficient of LOW level input voltage		_	-1.4	_	mV/K
V <sub>IH</sub>	HIGH level input voltage		2.3	_	2.5	V
CAP-DC		•				
I <sub>sink</sub>	output sink current		10.1	15.5	20.9	μΑ
I <sub>source</sub>	output source current		-20.9	-15.5	-10.1	μΑ
I <sub>sink</sub> /I <sub>source</sub>	ratio of sink to source current		0.9	1.025	1.15	
V <sub>IL</sub>	LOW level input voltage	T <sub>amb</sub> = 25 °C	825	850	875	mV
$\frac{\Delta V_{IL}}{\Delta T}$	temperature coefficient of LOW level input voltage		-	-1.4	_	mV/K
V <sub>IH</sub>	HIGH level input voltage		2.3	_	2.5	V

#### **Notes**

- 1. An unstabilized supply can be used.
- 2.  $V_{VMOT} = V_P$ ; all other inputs at 0 V; all outputs at  $V_P$ ;  $I_O = 0$  mA.
- 3. Switching levels with respect to driver outputs OUT-NA, OUT-NB, OUT-NC, OUT-PA, OUT-PB and OUT-PC.

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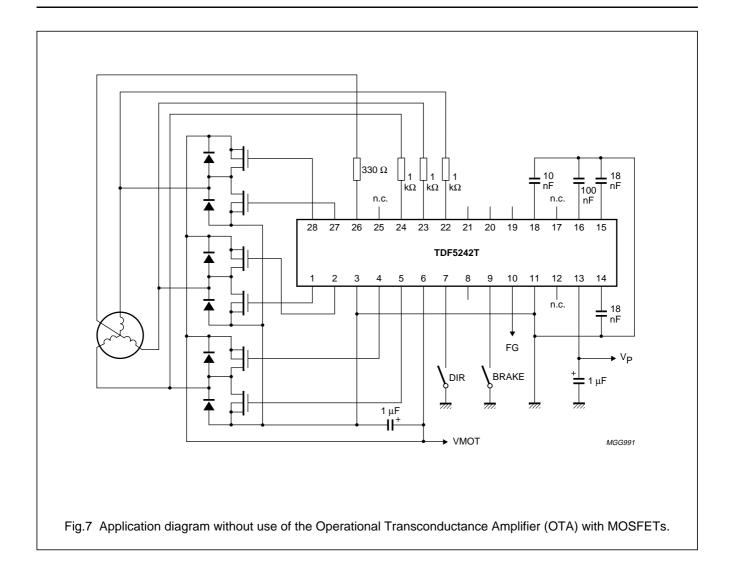
#### **APPLICATION INFORMATION**



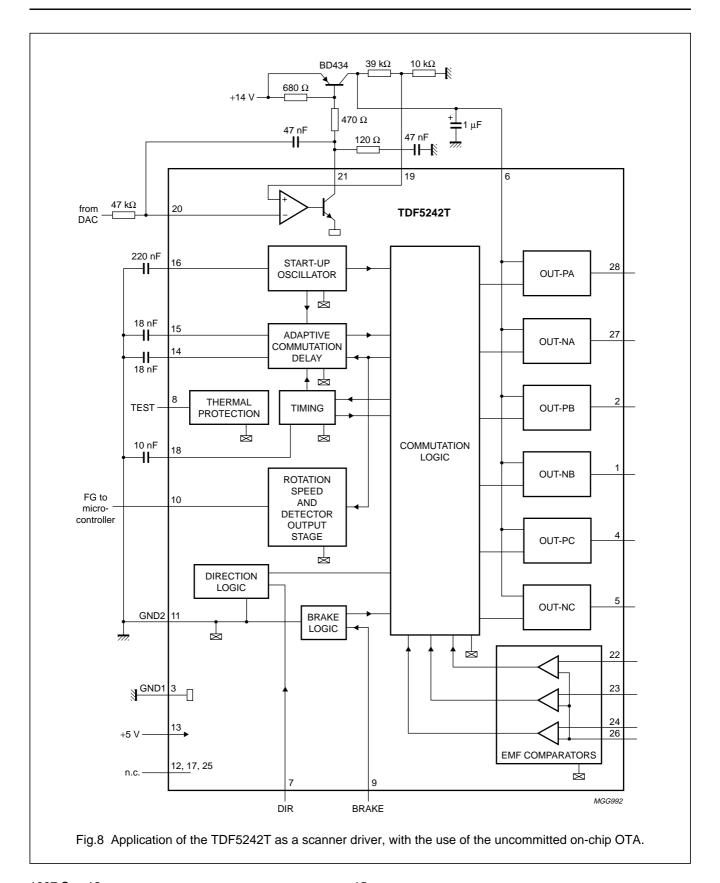
(1) RX = RY > 8 (VMOT - 1.5).

Fig.6 Application diagram without use of the Operational Transconductance Amplifier (OTA) with bipolar power transistors.

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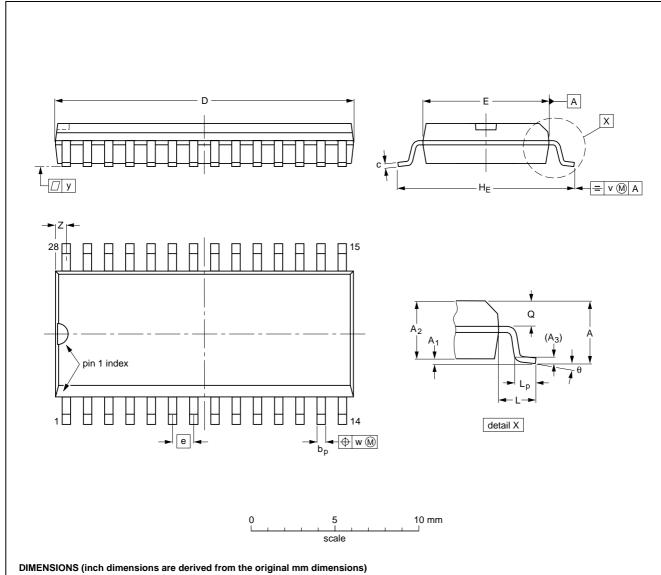


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#### **PACKAGE OUTLINE**

SO28: plastic small outline package; 28 leads; body width 7.5 mm

SOT136-1



UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	e	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	18.1 17.7	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004		0.01	0.019 0.014	0.013 0.009	0.71 0.69	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN			
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE		
SOT136-1	075E06	MS-013AE			<del>-95-01-24</del> 97-05-22		

**TDF5242T** 

#### **SOLDERING**

#### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

#### Reflow soldering

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

#### Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### Repairing soldered joints

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300  $^{\circ}$ C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320  $^{\circ}$ C.

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#### **DEFINITIONS**

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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**NOTES** 

# Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113,

Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213, Tel. +43 160 1010,

Fax. +43 160 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,

220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773

Belgium: see The Netherlands Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor,

51 James Bourchier Blvd., 1407 SOFIA, Tel. +359 2 689 211, Fax. +359 2 689 102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,

Tel. +1 800 234 7381

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,

72 Tat Chee Avenue, Kowloon Tong, HONG KONG,

Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America Czech Republic: see Austria

Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S,

Tel. +45 32 88 2636, Fax. +45 31 57 0044 Finland: Sinikalliontie 3, FIN-02630 ESPOO, Tel. +358 9 615800, Fax. +358 9 61580920

France: 4 Rue du Port-aux-Vins. BP317. 92156 SURESNES Cedex.

Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,

Tel. +49 40 23 53 60, Fax. +49 40 23 536 300

Greece: No. 15, 25th March Street, GR 17778 TAVROS/ATHENS,

Tel. +30 1 4894 339/239, Fax. +30 1 4814 240

Hungary: see Austria

India: Philips INDIA Ltd, Band Box Building, 2nd floor, 254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,

Tel. +91 22 493 8541, Fax. +91 22 493 0966

Indonesia: see Singapore

Ireland: Newstead, Clonskeagh, DUBLIN 14, Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,

TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007 Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3, 20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108,

Tel. +81 3 3740 5130, Fax. +81 3 3740 5077

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,

Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR, Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905, Tel. +9-5 800 234 7381

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,

Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,

Tel. +64 9 849 4160, Fax. +64 9 849 7811 Norway: Box 1, Manglerud 0612, OSLO, Tel. +47 22 74 8000, Fax. +47 22 74 8341

Philippines: Philips Semiconductors Philippines Inc., 106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI, Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Ul. Lukiska 10, PL 04-123 WARSZAWA, Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain Romania: see Italy

Russia: Philips Russia, UI. Usatcheva 35A, 119048 MOSCOW,

Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231,

Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,

2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000,

Tel. +27 11 470 5911, Fax. +27 11 470 5494

South America: Rua do Rocio 220, 5th floor, Suite 51, 04552-903 São Paulo, SÃO PAULO - SP, Brazil, Tel. +55 11 821 2333, Fax. +55 11 829 1849 Spain: Balmes 22 08007 BARCELONA

Tel. +34 3 301 6312. Fax. +34 3 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,

Tel. +46 8 632 2000, Fax. +46 8 632 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,

Tel. +41 1 488 2686, Fax. +41 1 481 7730

Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1, TAIPEI, Taiwan Tel. +886 2 2134 2865, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.

209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,

Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL,

Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,

252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Haves. MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421 United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,

Tel. +1 800 234 7381 Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,

Tel. +381 11 625 344, Fax.+381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

Internet: http://www.semiconductors.philips.com

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